

APPLICABLE STANDARD									
Rating	Operating Temperature Range		-55 °C to 85 °C ⁽¹⁾		Storage Temperature Range		-10 °C to 60 °C ⁽²⁾		
	Voltage		50 V AC		Storage Humidity Range		Relative humidity 85% max (Not dewed)		
	Current		0.7 A		Operating Humidity Range				
SPECIFICATIONS									
ITEM		TEST METHOD			REQUIREMENTS			QT	AT
CONSTRUCTION									
General Examination		Visually and by measuring instrument.			According to drawing.			x	x
Marking		Confirmed visually.						x	x
ELECTRIC CHARACTERISTICS									
Contact Resistance		100 mA(DC or 1000Hz)			70m Ω MAX.			x	—
Insulation Resistance		100 V DC.			100 M Ω MIN.			x	—
Voltage Proof		150 V AC for 1 min.			No flashover or breakdown.			x	x
MECHANICAL CHARACTERISTICS									
Insertion and Withdrawal Forces		Measured by applicable connector.			Insertion Force: 36 N MAX. Withdrawal Force: 3.6 N MIN.			x	—
Mechanical Operation		50 times insertions and extractions.			① Contact Resistance : 80m Ω MAX. ② No damage, crack and looseness of parts.			x	—
Vibration		Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.			① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.			x	—
Shock		490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.						x	—
ENVIRONMENTAL CHARACTERISTICS									
Damp Heat (Steady state)		Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			① Contact Resistance : 80m Ω MAX. ② Insulation Resistance:100 M Ω MIN. ③ No damage, crack and looseness of parts.			x	—
Rapid Change of Temperature		Temperature -55 → +85 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber : within 2~3 MIN)						x	—
Cold		Exposed at -55°C, 96 h			① Contact Resistance : 80m Ω ② No damage, crack and looseness of parts.			x	—
Dry Heat		Exposed at 85°C, 96 h						x	—
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: JIS C 60068)			① No defect such as corrosion which impairs the function of connector. ② Contact Resistance : 80m Ω			x	—
Resistance to Soldering Heat		1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 2) Soldering irons : 360°C MAX. for 5 sec.						x	—
Solderability		Soldered at solder temperature 245±3°C for immersion duration, 3 sec.			A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.			x	—
	COUNT	DESCRIPTION OF REVISIONS			DESIGNED		CHECKED		DATE
△									
REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB.					APPROVED	HS. OKAWA		14. 09. 30	
					CHECKED	KN. SHIBUYA		14. 09. 30	
					DESIGNED	AH. EDASHIGE		14. 09. 30	
					DRAWN	AH. EDASHIGE		14. 09. 30	
Unless otherwise specified, refer to JIS-C-5402.									
Note QT:Qualification Test AT:Assurance Test X:Applicable Test					DRAWING NO.		ELC4-352596-00		
HRS		SPECIFICATION SHEET			PART NO.		FX22-40P-0. 5SH		
		HIROSE ELECTRIC CO., LTD.			CODE NO.		CL572-3001-4-00		△

